

Analog Devices Inc, Hillview Assembly Site Transfer

Qualification Results and Summary of ADI Philippines Assembly of TO5 Non-RH devices

TEST	SPECIFICATION TO MIL-STD-883	SAMPLE SIZE TOTAL OF 2 LOTS	RESULTS
Resistance to Solvents	Resistance to Solvents Method 2015	N/A LASER	N/A
Solderability	Method 2003	5 units	PASS
Bond Pull	Method 2011, Cond D	5 units	PASS
Operating Life	Method 1005	90 units	PASS
Physical Dimensions	Method 2016	15 units	PASS
Lead Integrity followed by Fine & Gross Leak	Method 2004, Cond. B2	15 units	PASS
	Method 1014, Cond. A and C	15 units	PASS
Thermal Shock, Temperature Cycling, Moisture Resistance, and Fine & Gross Leak	Thermal Shock Method 1011, Cond. B	30 units	PASS
	Temperature Cycling Method 1010, Cond. C	30 units	PASS
	Moisture Resistance Method 1004	30 units	PASS
	Method 1014, Cond. A and C	30 units	PASS
Mechanical Shock, Vibration Var. Freq., Constant Acceleration, and Fine & Gross Leak	Method 2002, Cond. B	30 units	PASS
	Method 2007, Cond. A	30 units	PASS
	Method 2001, Cond. E	30 units	PASS
	Method 1014, Cond. A and C	30 units	PASS
Salt Atmosphere and Fine & Gross Leak	Salt Atmosphere Method 1009, Cond. A	30 units	PASS
	Fine Leak/Gross Leak Method 1014, Cond. A and C	30 units	PASS
Internal Water Vapor	Method 1018	3 units	PASS
Adhesion of Lead Finish	Method 2025	15 leads	PASS
Lid Torque	Method 2024	5 units	PASS
Die Shear	Method 2019	5 units	PASS
High Temperature Storage	150C/1000hr	77 units	PASS